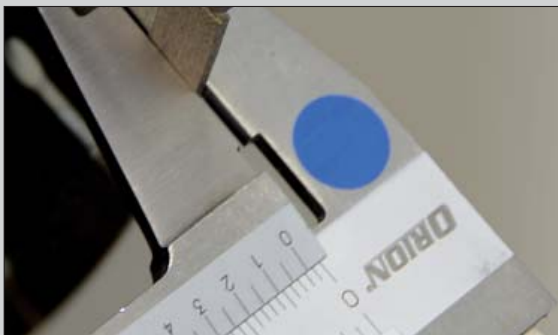
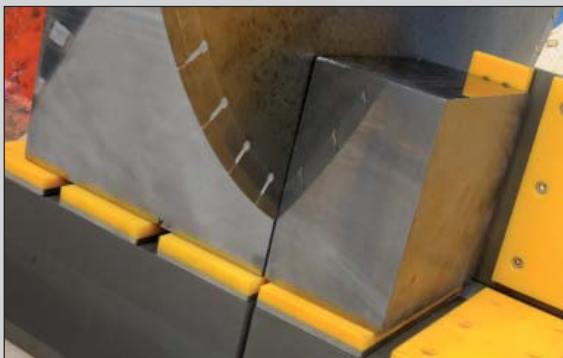




## 72 | 360

OD CROPPING SAW



Diamatbelagbreite  $\leq$  1,5 mm

This machine is suitable for cutting squared multi and mono crystalline silicon work pieces with a length of 50 up to 550 mm. The shortest cut off length is 10 mm.

- equipped for manual and fully automatic loading, for instance with help of an industrial robot
- thin blade water hydraulic guidance for thin diamond cutting discs  $\rightarrow$  kerf loss  $<$  1.7 mm
- compact design
- very low tool costs  $\rightarrow$  wheel life time between 12.000 and 15.000 cuts
- high process stability
- low investment costs
- high machine availability 97% acc. to SEMI E10
- cutting force control for an optimized cutting process and to avoid tool damages caused by SiC-inclusions
- cut off less than 10mm with vacuum chuck possible

#### Specifications:

- arithmetical surface roughness  $R_a \leq 0,8 \mu\text{m}$
- average surface roughness  $R_z \leq 8 \mu\text{m}$
- parallelism  $< 0,2 \text{ mm}$
- angle tolerance  $< 0,3 \text{ mm}$
- evenness  $< 0,1 \text{ mm}$

#### Throughput:

- cycle time  $\leq 10$  minutes per cut (incl. loading, unloading)
- for work piece format 156 mm x 156 mm